

STPS140-Y

Automotive power Schottky rectifier

Features

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount miniature packages
- Avalanche capability specified
- AEC-Q101 qualified
- ECOPACK[®]2 compliant component

Description

Single chip Schottky rectifiers suited to Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in SMA and SMB, this device is especially intended for surface mounting and used in low voltage, high frequency inverters, free wheeling and polarity protection for automotive applications.

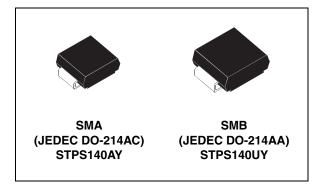


Table 1. Device summary

Symbol	Value
I _{F(AV)}	1 A
V_{RRM}	40 V
T _{j (max)}	150 °C
V _{F (max)}	0.5 V

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1 Characteristics

Table 2. Absolute Ratings (limiting values)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak revers	e voltage		40	V
I _{F(RMS)}	Forward rms voltage			7	Α
	Average forward SMA		$T_L = 130 ^{\circ}\text{C} \delta = 0.5$	1	Α
I _{F(AV)}	current	SMB	$T_L = 135$ °C $\delta = 0.5$	'	Α
I _{FSM}	Surge non repetitive forward current		t _p =10 ms sinusoidal	60	Α
I _{RRM}	Repetitive peak reverse current		$t_p = 2 \mu s F = 1 \text{ kHz square}$	1	Α
I _{RSM}	Non repetitive peak reverse current		t _p = 100 μs square	1	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 1$		t _p = 1 μs Tj = 25 °C	900	W
T _{stg}	Storage temperature range			- 65 to + 150	°C
Tj	Operating junction temperature range ⁽¹⁾			- 40 to + 150	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/µs

^{1.} $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit	
В	Junction to lead	SMA	30	°C/W
R _{th(j-l)}	Junction to lead	SMB	25	C/VV

Table 4. Static electrical characteristics

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
ı (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	V - V			12	μΑ
'R`		T _j = 100 °C	$V_R = V_{RRM}$		0.25	2	mA
	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 1 A			0.55	
V (2)		T _j = 125 °C			0.43	0.5	V
V _F `′		T _j = 25 °C				0.65	V
		T _j = 125 °C	I _F = 2 A		0.53	0.6	

^{1.} Pulse test: $tp = 380 \mu s$, $\delta < 2\%$

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To evaluate the conduction losses use the following equation: $P = 0.4 \times I_{F(AV)} + 0.10 I_{F^2(RMS)}$

^{2.} Pulse test: tp = 5 ms, δ < 2%

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Figure 1. Average forward power dissipation Figure 2. Average forward current versus awerage forward current ambient temperature (δ = 0.5)

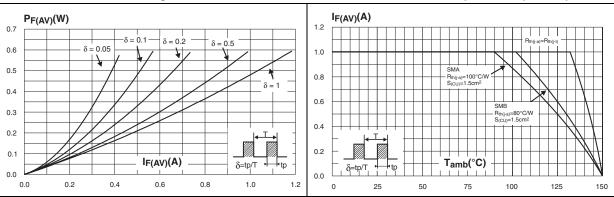


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

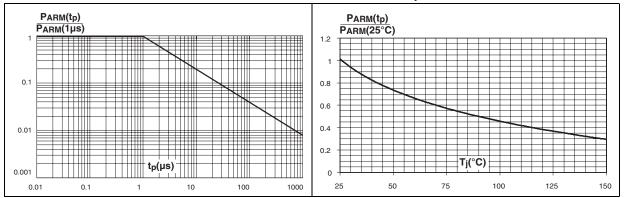
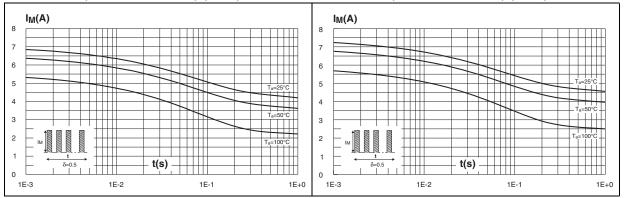


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values) (SMA)

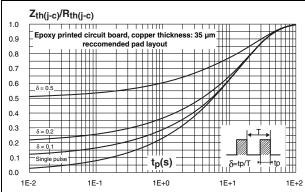
Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values) (SMB)



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Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)

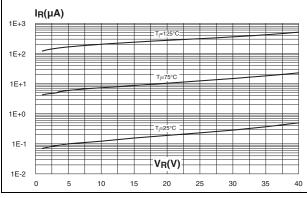
Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)



 $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 Epoxy printed circuit board, copper thickness: 35 μm reccomended pad layout 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 0.1 t_p(s) 0.0 1E-2 1E-1 1E+0 1E+1 1E+3

Figure 9. Reverse leakage current versus reverse voltage applied (typical values)

Figure 10. Junction capacitance versus reverse voltage applied (typical values)



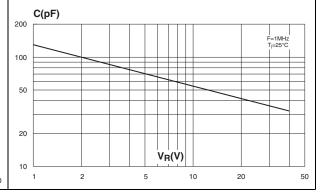
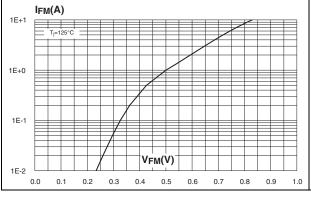
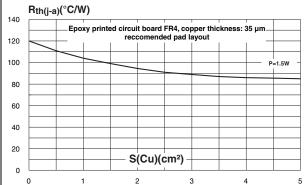


Figure 11. Forward voltage drop versus forward current (maximum values)

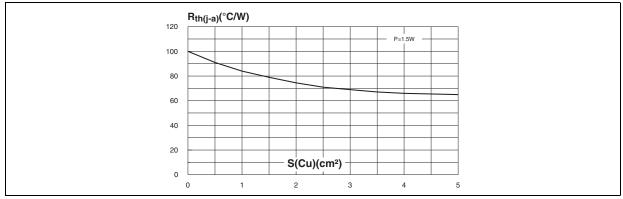
Figure 12. Thermal resistance junction to ambient versus copper surface under each lead (SMA)





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Figure 13. Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35 µm) (SMB)



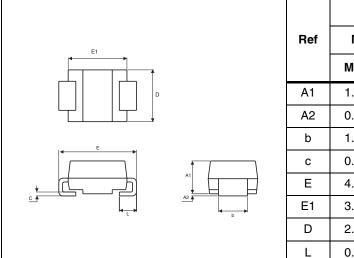
Package information STPS140-Y

2 Package information

- Band indicates cathode
- Epoxy meets UL94, V0

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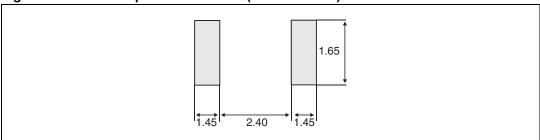
Figure 14. SMA package mechanical data



Ref	Millimeters		Inc	nes	
	Min. Max.		Min.	Max.	
A1	1.90	2.03	0.075	0.080	
A2	0.05	0.20	0.002	0.008	
b	1.25	1.65	0.049	0.065	
С	0.15	0.41	0.006	0.016	
Е	4.80	5.60	0.189	0.220	
E1	3.95	4.60	0.156	0.181	
D	2.25	2.95	0.089	0.116	
L	0.75	1.60	0.030	0.063	

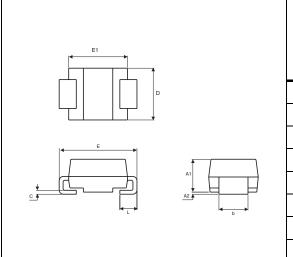
Dimensions

Figure 15. SMA footprint dimensions (in millimeters)



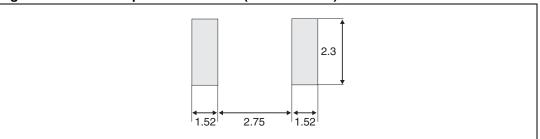
STPS140-Y Package information

Figure 16. SMB package mechanical data



	Dimensions				
Ref	Millimeters		Inches		
	Min. Max.		Min.	Max.	
A1	1.90	2.45	0.075	0.096	
A2	0.05	0.20	0.002	0.008	
b	1.95	2.20	0.077	0.087	
С	0.15	0.41	0.006	0.016	
Е	5.10	5.60	0.201	0.220	
E1	4.05	4.60	0.159	0.181	
D	3.30	3.95	0.130	0.156	
L	0.75	1.60	0.030	0.063	

Figure 17. SMB footprint dimensions (in millimeters)



Ordering information STPS140-Y

3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS140A	S140Y	SMA	0.068 g	5000	Tape and reel
STPS140U	G14Y	SMB	0.107 g	2500	Tape and reel

4 Revision history

Table 6. Document revision history

Date	Revision	Changes
10-Dec-2010	1	First issue.

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